

WB100-e

MANUAL & SEMI-AUTOMATIC WIRE BONDER

A manual and semi-automatic wire bonder for precise wedge and ball bonding with fine wire from 17 μm to 50 μm .



WEDGE & BALL BONDING

MOTORIZED Z-AXIS

TOUCHSCREEN

17–50 μm WIRE
RANGE

Flexible by design

The WB100-e combines precise manual control with semi-automatic functions. It is designed for R&D, prototyping, process development, repair work and flexible small-series production.

Explore the possibilities

Contact Micronnect for configuration advice, a demonstration, training and service.

KEY BENEFITS

- High positioning accuracy
- Fast changeover between applications
- Ergonomic and intuitive operation
- Configurations for wedge and ball bonding

Technology and configuration

A compact manual and semi-automatic wire bonder with extensive process control for laboratory and flexible production environments.

01 Operation

10-inch touchscreen with clear recipe settings and program storage.

02 Bonding modes

Wedge and ball bonding with manual or semi-automatic process sequences.

03 Mechanics

Motorized Z-axis, step-back Y and a movable table for accurate positioning.

04 Process control

Adjustable bond force, bond power, bond time, loop height and search height, with automatic bond height detection.

TECHNICAL DATA

Bonding area	165 × 165 mm
Z travel	40 mm
Table ratio	8:1
Ultrasonic system	PLL, 62 kHz
Bond time	0–10.000 ms
Capillary / tool	Ø 1,58 mm
Dimensions	450 × 600 × 500 mm
Weight	27 kg

Specifications are based on the supplied product information. Final execution may vary by configuration.

OPTIONS

- Heated workholder
- Automatic wire despooler
- Loop profile
- Tool heater
- Additional light source
- Camera option

The automatic wire despooler provides controlled wire feeding and helps keep the fine wire securely guided, reducing the risk of the wire slipping out during operation.

Find the right configuration for your process

Contact us for technical advice or a demonstration.

CONTACT